

AMENDMENTS TO THE ABSTRACT

Please amend the Abstract as follows:

~~The present invention discloses a light emitting device package, comprising: includes a metal base;base, an electrical circuit layer provided at an upper side of the metal base for providing a conductive path;path, a light emitting device mounted in a second region having a smaller thickness than a first region on the metal base;base, an insulating layer sandwiched between the meta-metal base and the electrical circuit layer;layer, an electrode layer provided at an upper side of the electrical circuit layer;layer, and a wire for electrically connecting the electrode layer and the light emitting device. Further, there is provided aThe light emitting device package which is improved inhas improved light emission efficiency since the light emitting device is placed on a small thickness portion of the metal base.~~